Bluetooth Wireless Connectivity

Texas Instruments Incorporated (TI), leading the industry with the most complete wireless connectivity portfolio for embedded applications, today announced that its Bluetooth® v4.0 technology-based CC2560 and CC2564 wireless devices are now available in easy-to-integrate QFN packages offered by TI and its distribution partners. TI also announced the availability of additional production-ready modules based on the two devices, as well as software and tools. The QFN packages and various modules give customers choice regarding power, size and cost requirements.

The ROHS-compliant QFN packages of the CC2560 and CC2564 Bluetooth v4.0 devices are available today through TI and its distributors. To further help design efforts, TI encourages customers to download from its wiki a two-layer reference design (schematics, layout and bill of materials) that can be copied and pasted into end applications.

TI will release full-featured evaluation boards and design materials for hardware and software prototyping with the CC2560 and CC2564 QFN devices later this quarter.

In addition to the two modules previously announced, four new complete, validated and certified modules are now available from TI partners. The modules vary in size, temperature range and output power—including Class 1 and Class 2 versions. One module also offers a pre-integrated MCU plus CC2564 solution for faster development.

Software development kits for Bluetooth and Bluetooth/Bluetooth low energy solutions are currently available. Customers can also access sample applications and demos provided in source code showing API usage.

A royalty-free Bluetooth stack and various profiles are provided pre-integrated on MCUs such as TI’s ultra-low power MSP430™ MCU and Stellaris® ARM®

Cortex™-M3/M4 MCUs.

TI will also release an updated Bluetooth stack in mid-4Q 2012. The new stack will offer flexible software build options that will enable customers to select specific profiles to support. This capability allows for greater memory size optimization and the ability to support a broader range of MCUs.

The CC2560 device offers Bluetooth v4.0 “classic” support for audio and data applications requiring high throughput. The CC2564 device supports two options: dual-mode Bluetooth/Bluetooth low energy or dual-mode Bluetooth/ANT+. Applications that benefit from the dual-mode solution include those that require wireless communication to Bluetooth “classic” products and Bluetooth low energy or ANT+ devices such as sports and fitness aggregator gadgets or smart watches. The dual-mode Bluetooth v4.0 solution can also be used as a sensor solution that delivers longer range to communicate with mobile devices that may or may not have Bluetooth low energy technology.

Texas Instruments Incorporated
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